WHAT IS CLAIMED IS:

1. A method of bonding substrates, comprising:

depositing a layer of bonding substrate material onto a bonding surface of a first substrate;

increasing a bonding site density of at least one of the layer of bonding substrate material on said first substrate and a bonding surface of a second substrate; and

bonding the bonding surface of the first substrate having the layer of bonding substrate material to the bonding surface of the second substrate.

2. A method according to Claim 1, further comprising:

polishing the layer of bonding substrate material and the bonding surface of the second substrate prior to the step of increasing the bonding site density.

3. A method according to Claim 2, wherein the step of polishing includes using chemical-mechanical polishing.

4. The method according to Claim 2, wherein said step of polishing includes polishing said layer and said second substrate to angstrom-level flatness.

5. A method according to Claim 1, wherein the step of bonding comprises:

fusion bonding the first substrate and the second substrate at substantially room temperature to form a package.

6. A method according to Claim 5, wherein the step of bonding further comprises:

annealing the package for approximately two hours at approximately 200 °C.

7. The method according to Claim 1, wherein said step of depositing includes depositing tetraethoxysilane, amorphous silicon, silicon nitride or glass frit.

8. The method according to Claim 7, wherein first substrate is formed of glass.

9. The method according to Claim 8, wherein the second substrate is formed of tetraethoxysilane.

10. A method according to Claim 1, wherein the step of increasing the bonding site density comprises:

plasma treating at least one of the layer of bonding substrate material and the bonding surface of the second substrate.

11. A method according to Claim 10, wherein the step of increasing the bonding site density further comprises:

dipping the at least one of the layer of bonding substrate material and the bonding surface of the second substrate in at least one of de-ionized water and SC1 chemistry.

12. The method according to Claim 1, wherein the bonding substrate material, the first substrate and the second substrate each have a substantially identical refractive index.

13. A MEMS package, comprising:

a first substrate having a bonding surface;

a second substrate having a polished bonding surface facing the bonding surface of the first substrate; and

a polished layer of bonding substrate material deposited onto the bonding surface of the first substrate and fusion bonded to the polished bonding surface of the second substrate.

14. A MEMS package according to claim 13, wherein the polished bonding surface of the second substrate and the polished layer of bonding substrate material have Angstrom-level flatness.

15. A MEMS package according to claim 13, wherein the first substrate, the second substrate and the bonding substrate material each have a substantially identical refractive index.

16. A MEMS package according to claim 13, wherein the first substrate, the second substrate and the bonding substrate material form a hermetic seal around a MEMS device.

17. A digital projector, comprising:

a MEMS package, wherein the package comprises:

a first substrate having a bonding surface;

a second substrate having a polished bonding surface facing the bonding surface of the first substrate; and

a polished layer of bonding substrate material deposited onto the bonding surface of the first substrate and fusion bonded to the polished bonding surface of the second substrate.

18. A digital projector according to claim 17, wherein the polished bonding surface of the second substrate and the polished layer of bonding substrate material have Angstrom-level flatness.

19. A digital projector according to claim 17, wherein the first substrate, the second substrate and the bonding substrate material each have a substantially identical refractive index.

20. A digital projector according to claim 17, wherein the first substrate, the second substrate and the bonding substrate material form a hermetic seal around a MEMS device.

21. A MEMS package, comprising:

a first substrate having a bonding surface;

a second substrate having a polished bonding surface facing the bonding surface of the first substrate; and

means for bonding deposited onto the bonding surface of the first substrate and fusion bonded to the polished bonding surface of the second substrate.

22. A MEMS package formed by a method comprising the steps of:

depositing a layer of bonding substrate material onto a bonding surface of a first substrate;

increasing a bonding site density of at least one of either the layer of bonding substrate material on said first substrate or a bonding surface of a second substrate; and

bonding the bonding surface of the first substrate having the layer of bonding substrate material to the bonding surface of the second substrate.